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electronic components and fluorescent tubes

2.2.2 Lead in high melting temperature type solders2.2.3 Lead in solders for servers, storage and storage array systems; 2.2.4 Lead in solders for network infrastructure equipment; 2.2.5 Lead in electronic ceramic parts; 2.3 Impact of Exemptions; 2.3.1 Military electronics; 2.3.2 Automotive electronics; 2.3.3 Avionics; 2.3.4 Oil and gas well electronics; 2.3.5 Medical electronics; 2.3.6 Industrial. network infrastructure, server and storage electronics; 2.3.7 Risks due to exemptions; 2.4 Compliance with the Legislation; 2.5 Recommendations and Conclusions; 2.6 References
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4.10.1 Materials considerations for wave soldering

Sommario/riassunto

Lead-free Electronics provides guidance on the design and use of lead-free electronics as well as technical and legislative perspectives. All the complex challenges confronting the elec-tronics industry are skillfully addressed:* Complying with state legislation* Implementing the transition to lead-free electronics, including anticipating associated costs and potential supply chain issues* Understanding intellectual property issues in lead-free alloys and their applications, including licensing and infringement* Implementing cost effective manufacturing and testing* Reducin